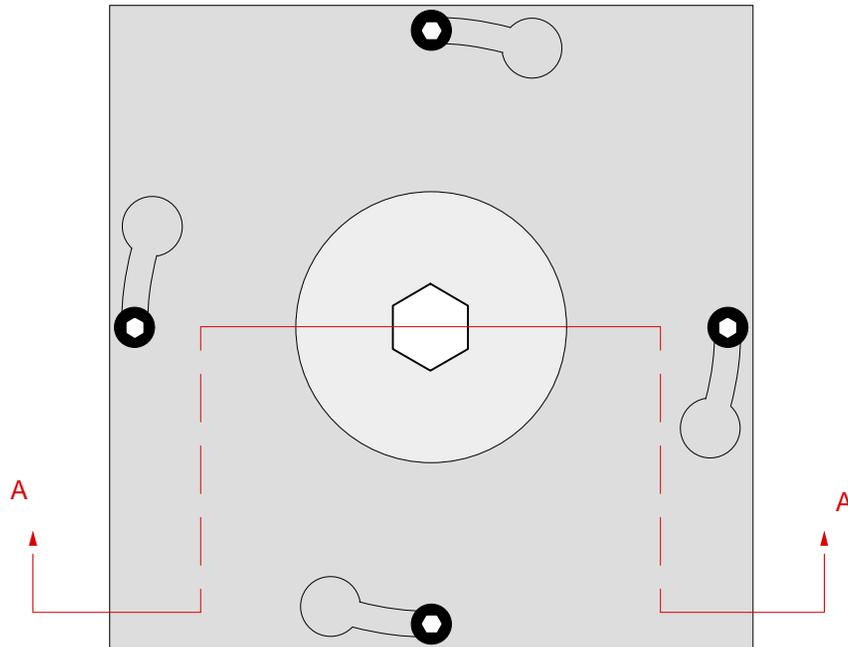


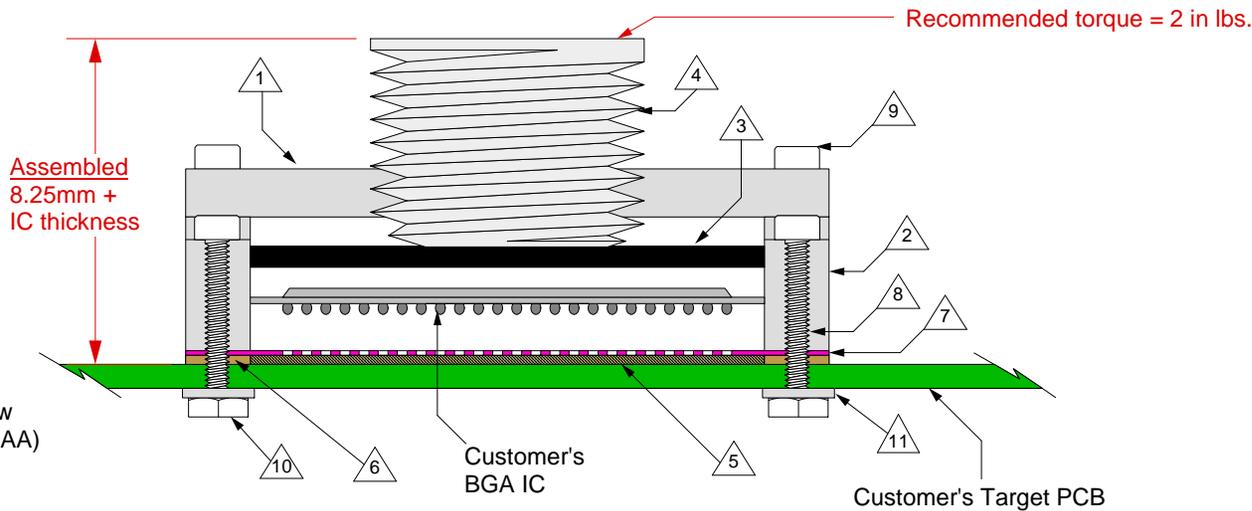
GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



Top View



Side View
(Section AA)

- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Cirlex. Thickness = 0.725mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 9 Socket lid screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 4.76mm long.
- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

SG-BGA-6070 Drawing

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Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

Drawing: H. Hansen

Date: 5/27/03

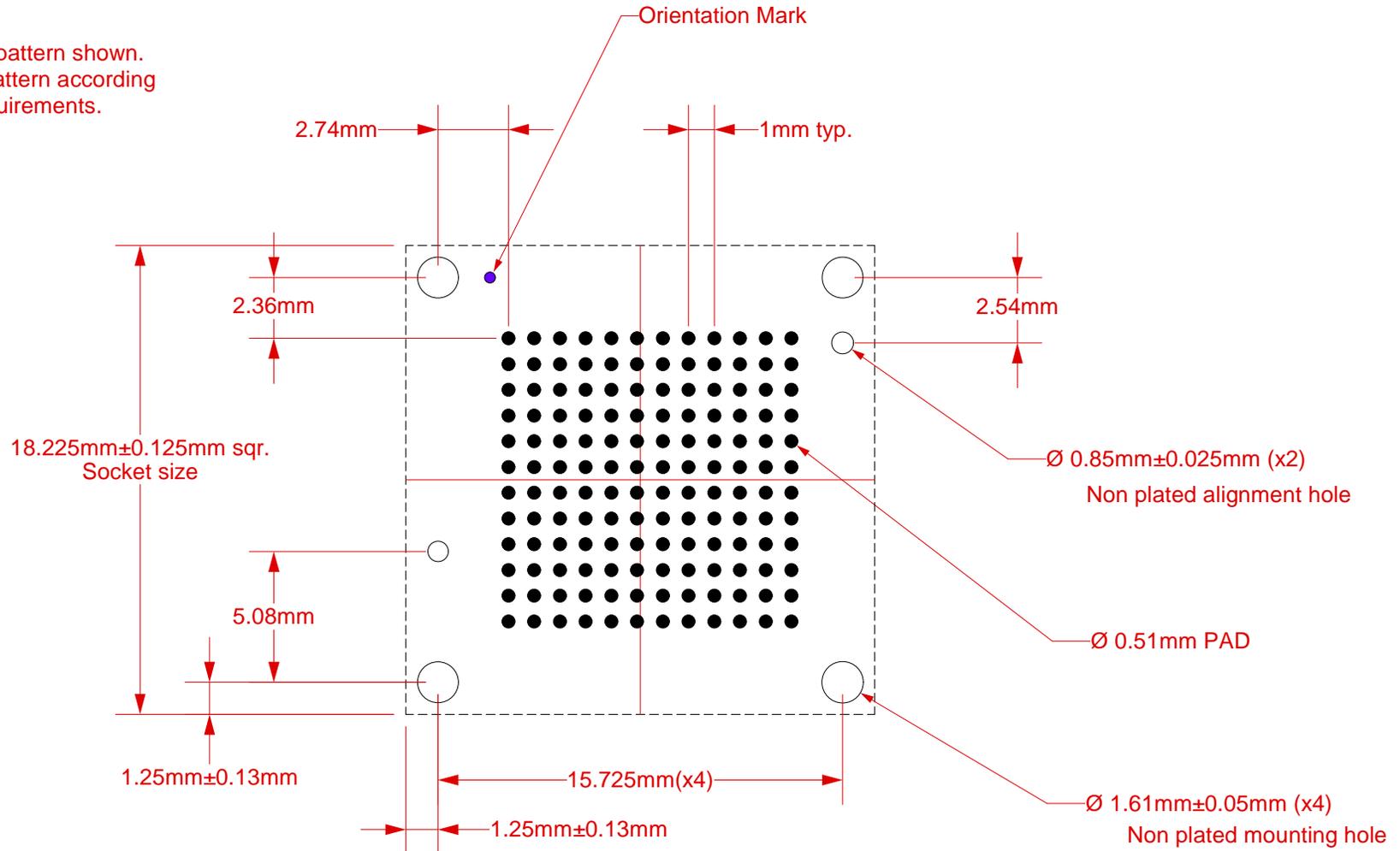
File: SG-BGA-6070 Dwg.mcd

Modified: 6/12/09, AE

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

Note: Full BGA pattern shown.
Please adjust pattern according
to individual requirements.



Target PCB Recommendations

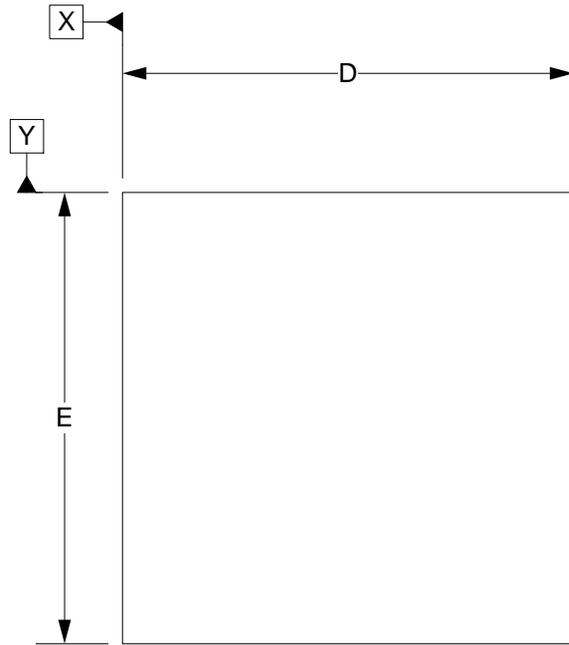
Total thickness: 1.6mm min.

Plating: Gold or Solder finish

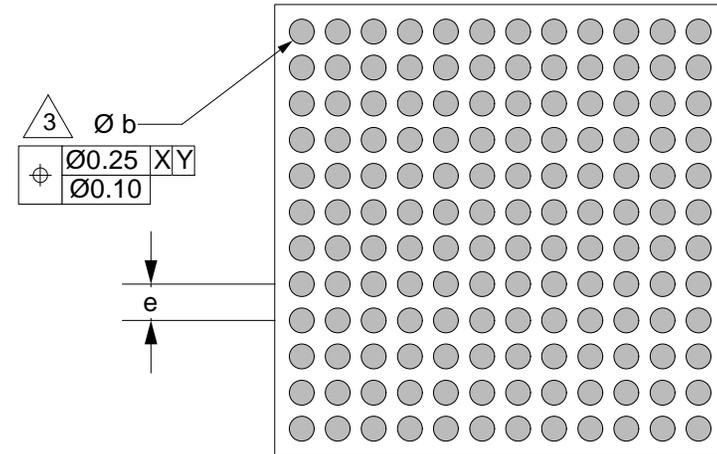
PCB Pad height: Same or higher than solder mask

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

SG-BGA-6070 Drawing		Status: Released	Scale: 3:1	Rev: B
 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: H. Hansen		Date: 5/27/03	
	File: SG-BGA-6070 Dwg.mcd		Modified: 6/12/09, AE	

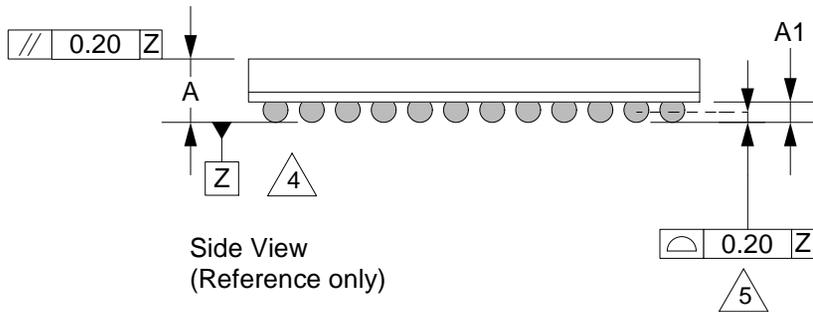


Top View
(Reference only)



Bottom View
(Reference only)

Array: 12x12



Side View
(Reference only)

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

- △ 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- △ 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- △ 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.97
A1	0.3	0.5
b		0.6
D	13.0 BSC	
E	13.0 BSC	
e	1.0 BSC	

	SG-BGA-6070 Drawing		Status: Released	Scale: -	Rev: B	
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com			Drawing: H. Hansen		Date: 5/27/03
				File: SG-BGA-6070 Dwg.mcd	Modified: 6/12/09, AE	